



TFW 1763/\$  
[10191/3935]

Inventor(s) : LAERMER ET AL.  
Filed : January 05, 2005  
Serial No. : 10/506,457  
For : DEVICE AND METHOD FOR ANISOTROPIC  
PLASMA ETCHING OF A SUBSTRATE,  
A SILICON BODY IN PARTICULAR  
Examiner : Allan W. Olsen  
Art Unit : 1763  
Confirmation No. : 9990

**Mail Stop Amendment**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Date: August 15, 2006  
Signature: Chili

**TRANSMITTAL**

SIR:

Please find a Response transmitted herewith for filing in the above-identified patent application.

Applicants hereby request a two-month extension of time for responding to the Office Action of March 30, 2006. The extended period for response expires on August 30, 2006. Please charge the \$450.00 extension fee and any other fee that may be required to **Deposit Account No. 11-0600**. A duplicate of this Transmittal is enclosed.

Dated: August 15, 2006

By:

Respectfully submitted,

Gerard A. Messina

Reg. No. 35,952

KENYON & KENYON LLP

One Broadway

New York, NY 10004

Telephone: (212) 425-7200

Facsimile: (212) 425-5288

**CUSTOMER NO. 26646**